

MBR40250G, MBR40250TG, MBRF40250TG, MBRB40250TG

Switch-mode Schottky Power Rectifier 250 V, 40 A

Features

- 250 V Blocking Voltage
- Low Forward Voltage Drop, $V_F = 0.86$ V
- Soft Recovery Characteristic, $T_{RR} < 35$ ns
- Stable Switching Performance Over Temperature
- These Devices are Pb-Free and are RoHS Compliant

Benefits

- Reduces or Eliminates Reverse Recovery Oscillations
- Minimizes Need for EMI Filtering
- Reduces Switching Losses
- Improved Efficiency

Applications

- Power Supply
- Power Management
- Automotive
- Instrumentation

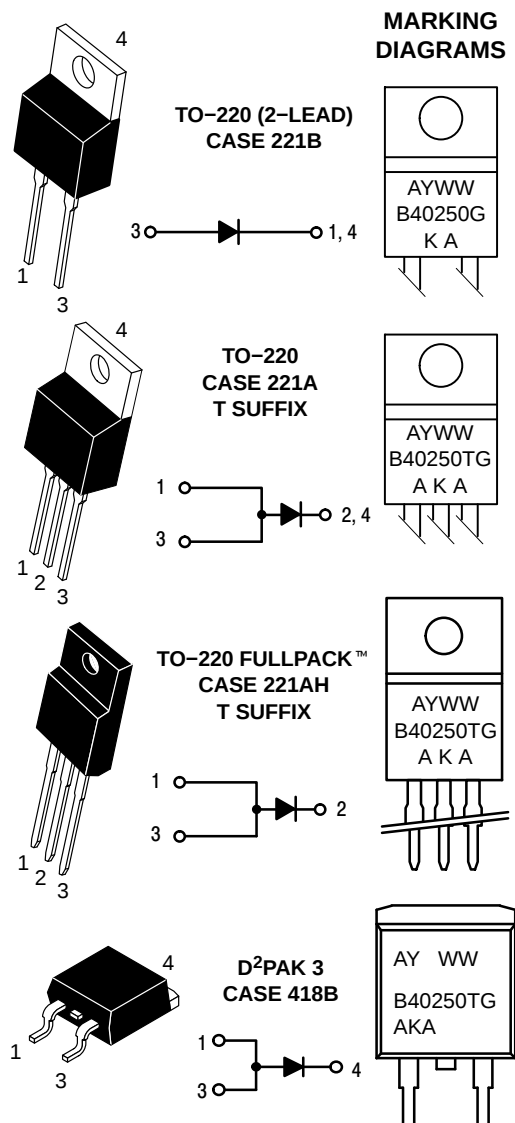
Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 1.9 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes:
260°C Max. for 10 Seconds
- Epoxy Meets UL 94 V-0 at 0.125 in



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B40250 = Device Code
T = 3 pins
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package
KA, AKA = Polarity Designator

ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	250	V
Average Rectified Forward Current (Rated V_R) $T_C = 82^\circ\text{C}$ MBR40250, MBR40250T, MBRB40250T (Rated V_R) $T_C = 46^\circ\text{C}$ MBRF40250T	$I_{F(AV)}$	40	A
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz) $T_C = 82^\circ\text{C}$ MBR40250, MBR40250T, MBRB40250T (Rated V_R , Square Wave, 20 kHz) $T_C = 46^\circ\text{C}$ MBRF40250T	I_{FRM}	80	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I_{FSM}	150	A
Storage Temperature	T_{stg}	- 65 to +175	$^\circ\text{C}$
Operating Junction Temperature	T_J	- 65 to +150	$^\circ\text{C}$
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/ μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Junction-to-Case MBR40250(T) and MBRB40250T MBRF40250	$R_{\theta JC}$	2.0 3.0	$^\circ\text{C/W}$
Junction-to-Ambient MBR40250(T) MBRF40250 MBRB40250T	$R_{\theta JA}$	60 50 50	

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) $I_F = 20\text{ A}$, $T_C = 25^\circ\text{C}$ $I_F = 20\text{ A}$, $T_C = 125^\circ\text{C}$ $I_F = 40\text{ A}$, $T_C = 25^\circ\text{C}$ $I_F = 40\text{ A}$, $T_C = 125^\circ\text{C}$	V_F	0.86 0.71 0.97 0.86	V
Maximum Instantaneous Reverse Current (Note 1) Rated DC Voltage, $T_C = 25^\circ\text{C}$ Rated DC Voltage, $T_C = 125^\circ\text{C}$	I_R	0.25 30	mA
Maximum Reverse Recovery Time $I_F = 1.0\text{ A}$, $di/dt = 50\text{ A}/\mu\text{s}$, $T_C = 25^\circ\text{C}$	t_{rr}	35	ns

DYNAMIC CHARACTERISTICS

Capacitance $V_R = -5.0\text{ V}$, $T_C = 25^\circ\text{C}$, Frequency = 1.0 MHz	C_T	500	pF
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Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

TYPICAL CHARACTERISTICS

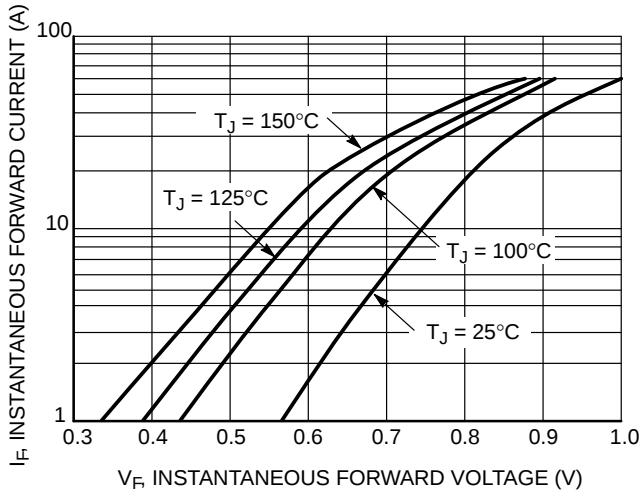


Figure 1. Typical Forward Voltage

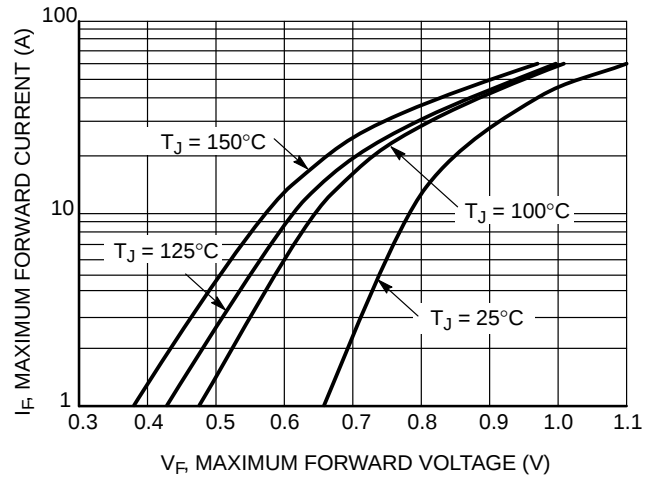


Figure 2. Maximum Forward Voltage

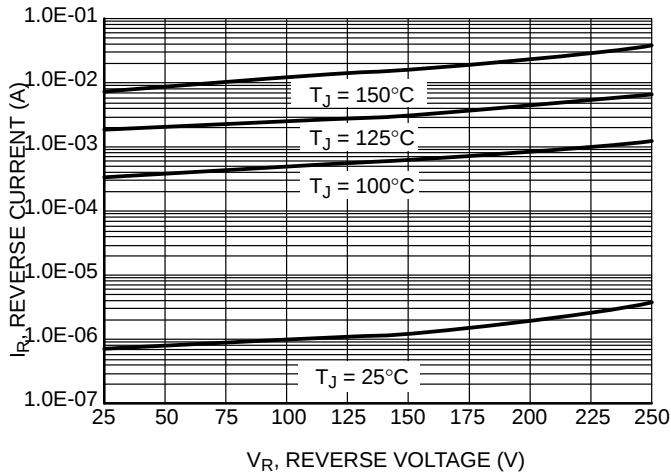


Figure 3. Typical Reverse Current

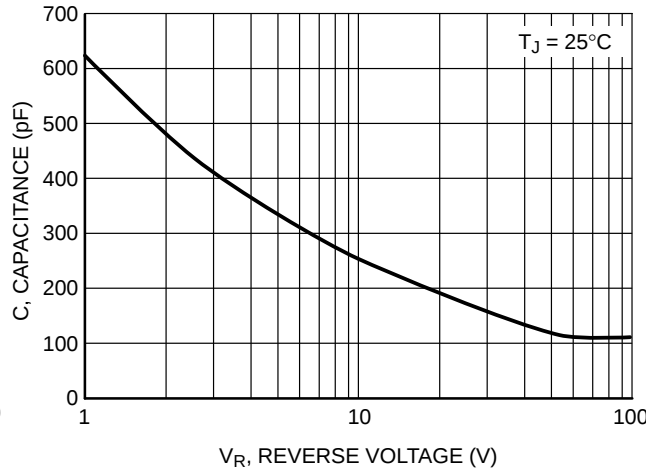


Figure 4. Typical Capacitance

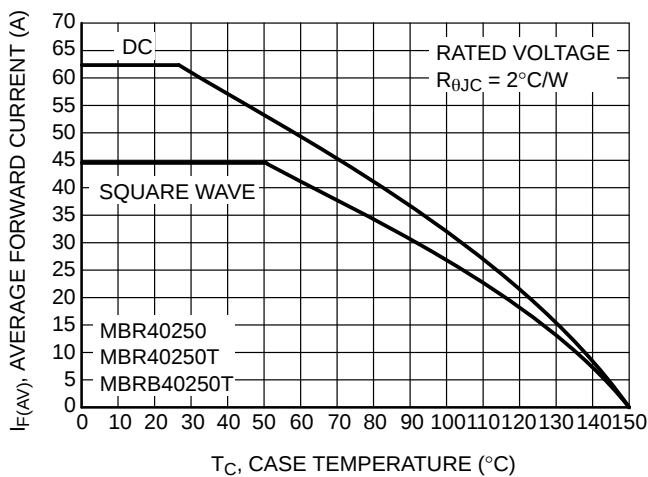


Figure 5. Current Derating (Case) for MBR40250, MBR40250T and MBRB40250T

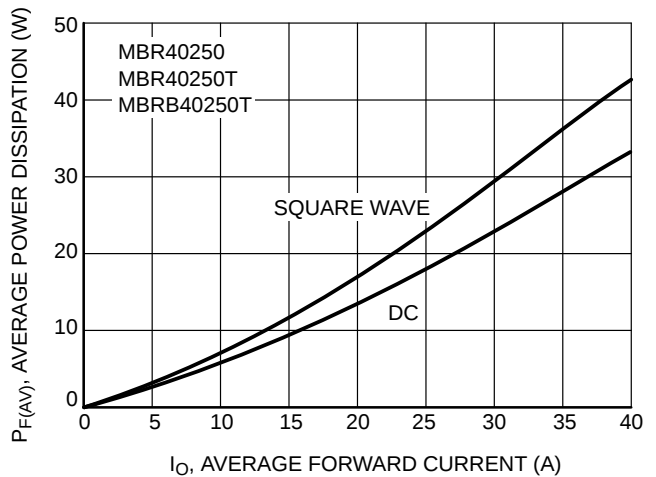


Figure 6. Forward Power Dissipation for MBR40250, MBR40250T and MBRB40250T

TYPICAL CHARACTERISTICS

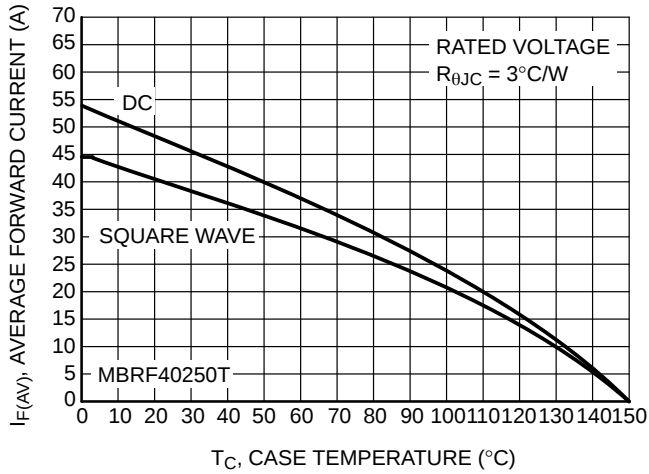


Figure 7. Current Derating (Case) for MBRF40250T

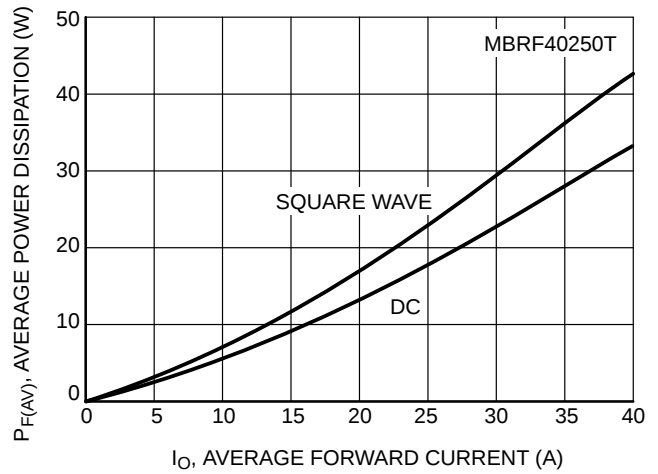


Figure 8. Forward Power Dissipation for MBRF40250T

ORDERING INFORMATION

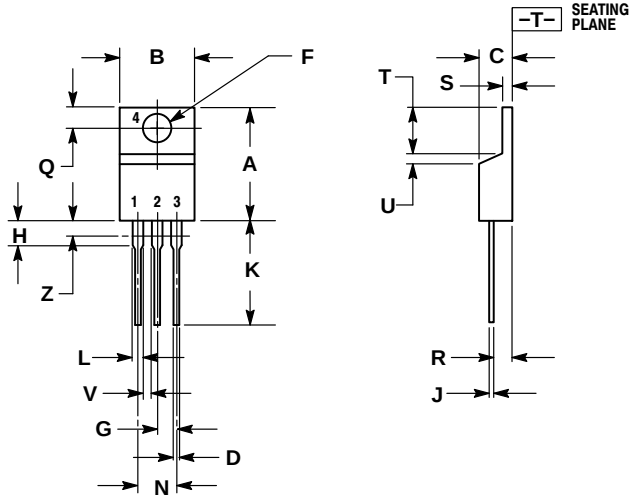
Device	Package	Shipping [†]
MBR40250G	TO-220 (2-LEAD) (Pb-Free)	50 Units / Rail
MBR40250TG	TO-220 (Pb-Free)	50 Units / Rail
MBRF40250TG	TO-220 FULLPACK (Pb-Free)	50 Units / Rail
MBRB40250TG	D ² PAK 3 (Pb-Free)	50 Units / Rail
MBRB40250TT4G	D ² PAK 3 (Pb-Free)	800 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MBR40250G, MBR40250TG, MBRF40250TG, MBRB40250TG

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 ISSUE AH

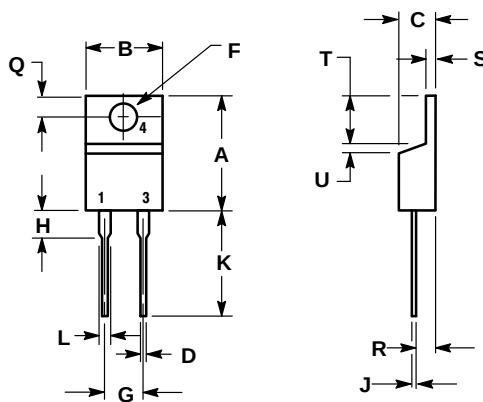


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.415	9.66	10.53
C	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
H	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

- STYLE 6:
- PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

TO-220, 2-LEAD CASE 221B-04 ISSUE F



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

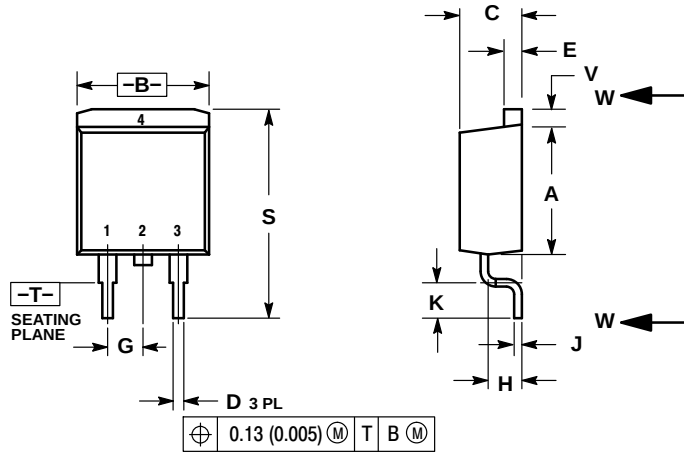
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.620	15.11	15.75
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.82
D	0.025	0.039	0.64	1.00
F	0.142	0.161	3.61	4.09
G	0.190	0.210	4.83	5.33
H	0.110	0.130	2.79	3.30
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.14	1.39
T	0.235	0.255	5.97	6.48
U	0.000	0.050	0.000	1.27

- STYLE 1:
- PIN 1. CATHODE
2. N/A
3. ANODE
4. CATHODE

MBR40250G, MBR40250TG, MBRF40250TG, MBRB40250TG

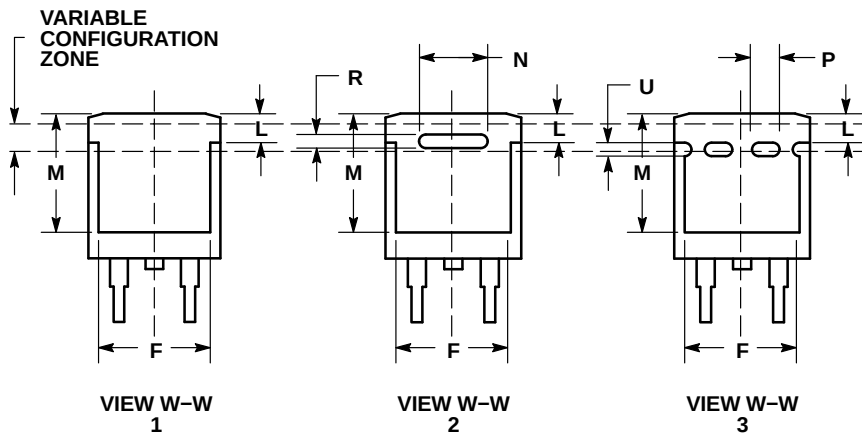
PACKAGE DIMENSIONS

D²PAK 3
CASE 418B-04
ISSUE K



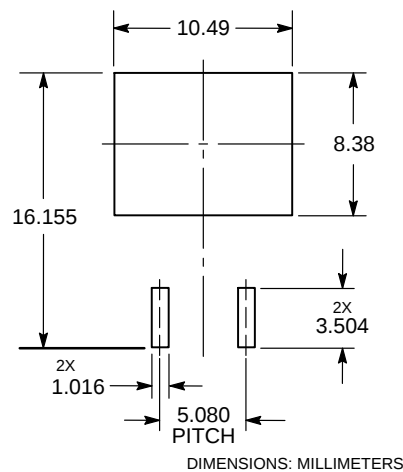
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



- STYLE 3:
1. ANODE
 2. CATHODE
 3. ANODE
 4. CATHODE

SOLDERING FOOTPRINT*



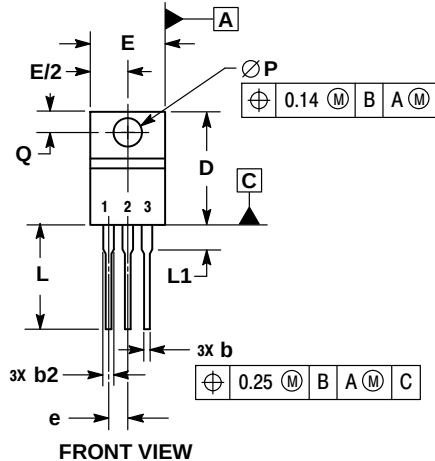
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MBR40250G, MBR40250TG, MBRF40250TG, MBRB40250TG

PACKAGE DIMENSIONS

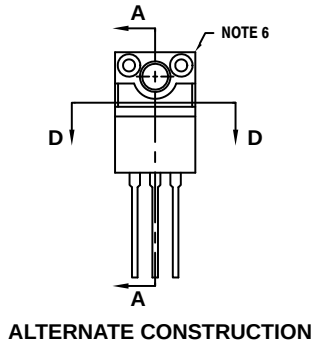
TO-220 FULLPAK, 3-LEAD CASE 221AH ISSUE F



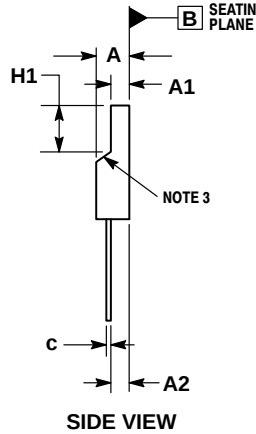
FRONT VIEW



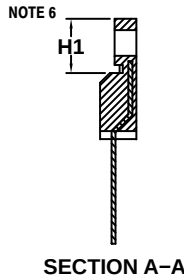
SECTION D-D



ALTERNATE CONSTRUCTION



SIDE VIEW



SECTION A-A

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR UNCONTROLLED IN THIS AREA.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE TO BE MEASURED AT OUTERMOST EXTREME OF THE PLASTIC BODY.
5. DIMENSION b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 2.00.
6. CONTOURS AND FEATURES OF THE MOLDED PACKAGE BODY MAY VARY WITHIN THE ENVELOPE DEFINED BY DIMENSIONS A1 AND H1 FOR MANUFACTURING PURPOSES.

DIM	MILLIMETERS	
	MIN	MAX
A	4.30	4.70
A1	2.50	2.90
A2	2.50	2.90
b	0.54	0.84
b2	1.10	1.40
c	0.49	0.79
D	14.70	15.30
E	9.70	10.30
e	2.54 BSC	
H1	6.60	7.10
L	12.50	14.73
L1	---	2.80
P	3.00	3.40
Q	2.80	3.20

STYLE 3:

- PIN 1. ANODE
- CATHODE
- ANODE

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MBR40250/D